

Features

- Operating voltage: 2.4V~12V
- Low power and high noise immunity CMOS technology
- Low standby current
- Three words transmission
- Built-in oscillator needs only 5% resistor
- Easy interface with an RF or infrared transmission media
- Minimal external components
- Pair with Holtek's 3¹⁸ series of decoders
- HT600/HT6207: 20-pin DIP/SOP package
HT680: 18-pin DIP/SOP package

Applications

- Burglar alarm system
- Smoke and fire alarm system
- Garage door controllers
- Car door controllers
- Car alarm system
- Security system
- Cordless telephones
- Other remote control systems

General Description

The 3¹⁸ encoders are a series of CMOS LSIs for remote control system applications. They are capable of encoding 18 bits of information which consists of N address bits and 18-N data bits. Each address/data input is externally trinary programmable if bonded out. It is otherwise set floating internally. Various packages of the 3¹⁸ encoders offer flexible combinations of programmable

address/data to meet various application needs. The programmable address/data is transmitted together with the header bits via an RF or an infrared transmission medium upon receipt of a trigger signal. The capability to select a TE trigger type or a DATA trigger type further enhances the application flexibility of the 3¹⁸ series of encoders.

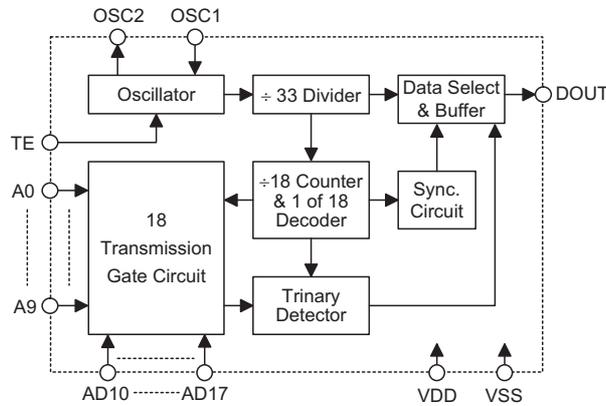
Selection Table

Function Part No.	Address No.	Address/ Data No.	Data No.	Dummy Code No.	Oscillator	Trigger	Package
HT600	9	5	0	4	RC oscillator	TE	20DIP/SOP
HT680	8	4	0	6	RC oscillator	TE	18DIP/SOP
HT6207	10	0	4	4	RC oscillator	D12~D15	20DIP/SOP

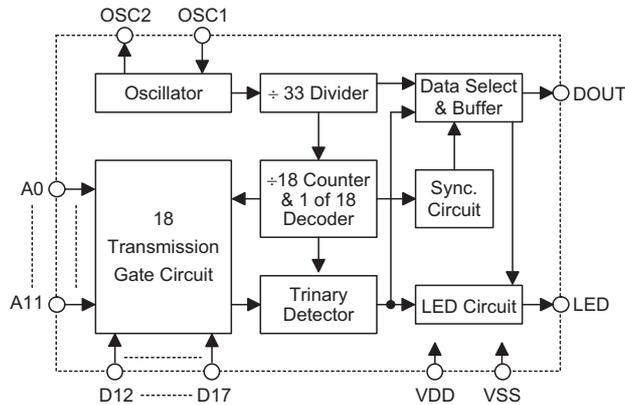
Note: Address/Data represents pins that can be either address or data according to the application requirement.

Block Diagram
TE Trigger

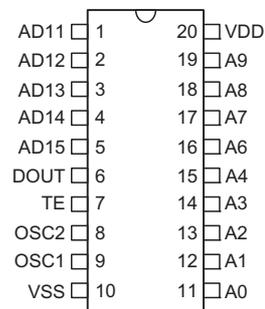
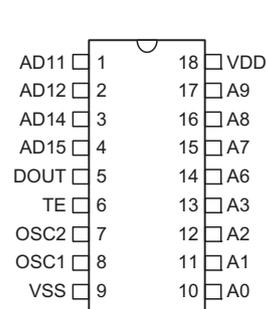
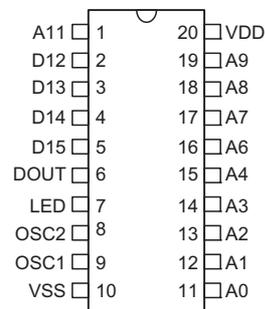
HT600/HT680


DATA Trigger

HT6207



Note: The address/data pins are available in various combinations.

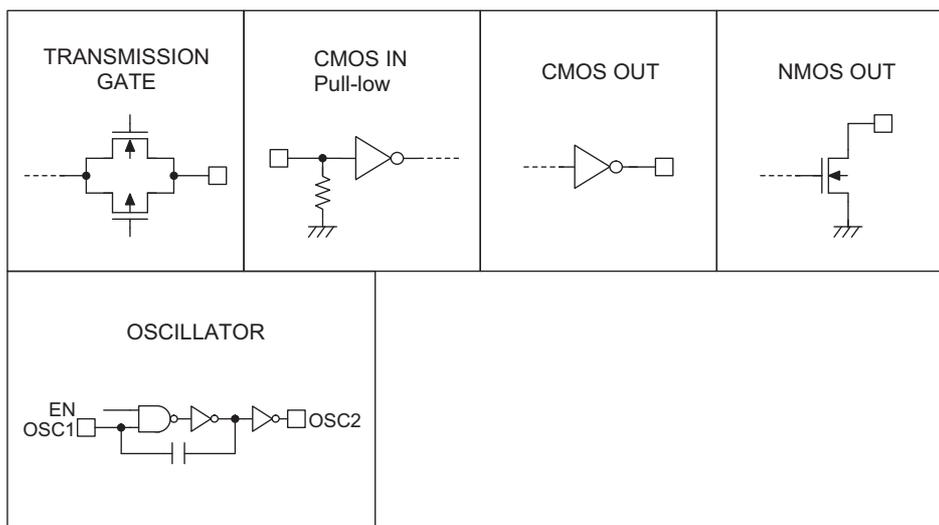
Pin Assignment
TE trigger type
DATA trigger type
**9-Address
5-Address/Data**

**HT600
- 20 DIP-A/SOP-A**
**8-Address
4-Address/Data**

**HT680
- 18 DIP-A/SOP-A**
**10-Address
4-Data**

**HT6207
- 20 DIP-A/SOP-A**

Pin Description

Pin Name	I/O	Internal Connection	Description
A0~A11	I	TRANSMISSION GATE	Input pins for address A0~A11 setting They can be externally set to VDD, VSS, or left open.
AD10~AD17	I	TRANSMISSION GATE	Input pins for address/data (AD10~AD17) setting They can be externally set to VDD, VSS, or left open.
D12~D15	I	CMOS IN Pull-low	Input pins for data (D12~D15) setting and transmission enable (active high) They can be externally set to VDD or left open (see Note).
DOUT	O	CMOS OUT	Encoder data serial transmission output
LED	O	NMOS OUT	LED transmission enable indicator
TE	I	CMOS IN Pull-low	Transmission enable, active high (see Note).
OSC1	I	OSCILLATOR	Oscillator input pin
OSC2	O	OSCILLATOR	Oscillator output pin
VSS	—	—	Negative power supply, ground
VDD	—	—	Positive power supply

Note: D12~D15 are data input and transmission enable pins of the HT6207.

TE is the transmission enable pin of the HT600/HT680.

Approximate Internal Connections

Absolute Maximum Ratings

Supply Voltage	$V_{SS}-0.3V$ to $V_{SS}+13V$	Storage Temperature	$-50^{\circ}C$ to $125^{\circ}C$
Input Voltage	$V_{SS}-0.3$ to $V_{DD}+0.3V$	Operating Temperature	$-20^{\circ}C$ to $75^{\circ}C$

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Electrical Characteristics

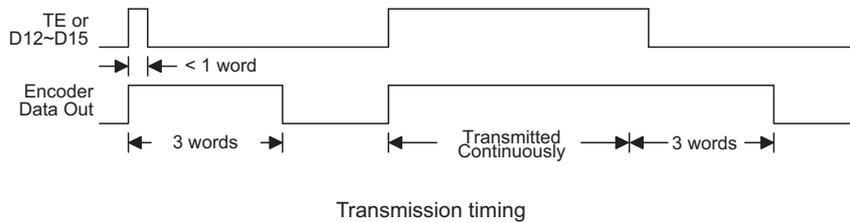
Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{DD}	Operating Voltage	—	—	2.4	—	12	V
I _{STB}	Standby Current	3V	Oscillator stops	—	0.1	1	μA
		12V		—	2	4	μA
I _{DD}	Operating Current	5V	No load, f _{OSC} =100kHz	—	250	500	μA
		12V		—	1200	2400	μA
I _{LED}	LED Sink Current	5V	V _{LED} =0.5V	1.5	3	—	mA
I _{DOUT}	Output Drive Current	5V	V _{OH} =0.9V _{DD} (Source)	-0.6	-1.2	—	mA
		5V	V _{OL} =0.1V _{DD} (Sink)	0.6	1.2	—	mA
V _{IH}	"H" Input Voltage	—	—	0.8V _{DD}	—	V _{DD}	V
V _{IL}	"L" Input Voltage	—	—	0	—	0.2V _{DD}	V
f _{OSC}	Oscillator Frequency	10V	R _{OSC} =330kΩ	—	100	—	kHz
R _{TE}	TE Pull-low Resistance	5V	V _{TE} =5V	—	1.5	3	MΩ
R _{DATA}	D12~D17 Pull-low Resistance	5V	V _{DATA} =5V	—	1.5	3	MΩ

Functional Description

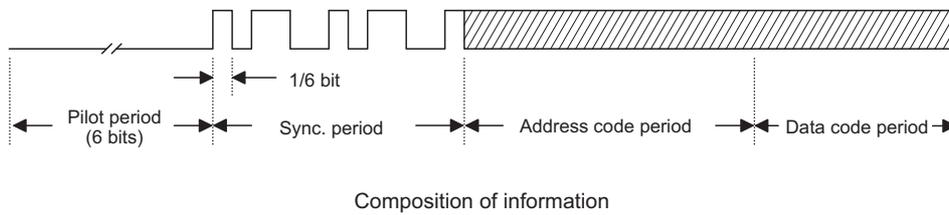
Operation

The 3¹⁸ series of encoders begins a three-word transmission cycle upon receipt of a transmission enable (TE for the HT600/HT680 or D12~D15 for the HT6207, active high). This cycle will repeat itself as long as the transmission enable (TE or D12~D15) is held high. Once the transmission enable falls low, the encoder output completes its final cycle and then stops as shown below.



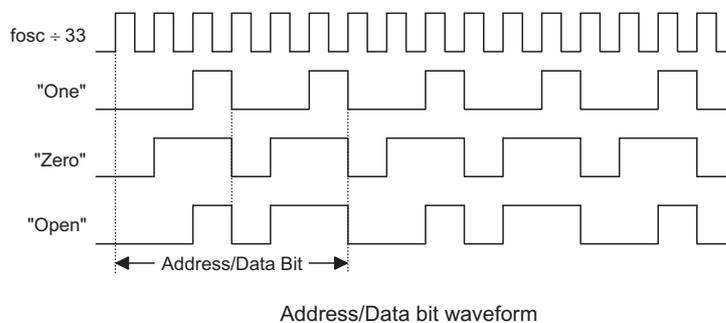
Information Word

An information word consists of four periods as shown:



Address/Data Waveform

Each programmable address/data pin can be externally set to one of the following three logic states:



The "Open" state data input is interpreted as logic low by the decoders since the decoder output only have two states.

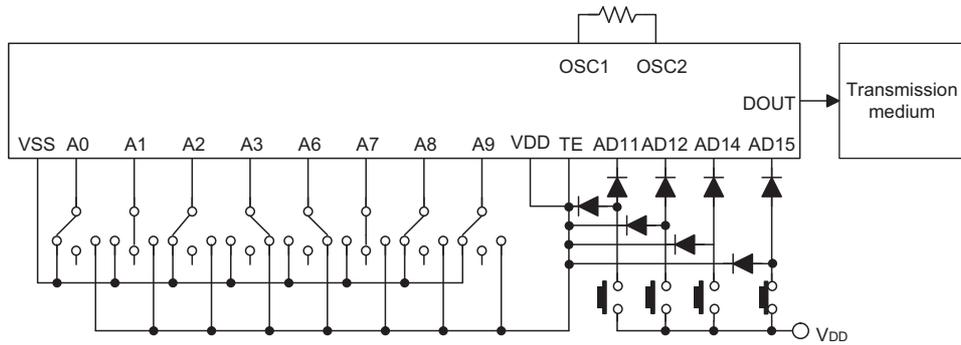
Address/Data Programming (Preset)

The status of each address/data pin can be individually preset to logic "high", "low", or "floating". If a transmission enable signal is applied, the encoder scans and transmits the status of the 18 bits of address/data serially in the order A0 to AD17 for the HT600/HT680 and A0 to D15 for the HT6207.

There are some packaging limitations. For example the 18-pin DIP HT680, offers four external data bits and eight external address bits. The remaining unpackaged bits or dummy codes are treated as floating for A0~AD17 or as pull-low for D12~D15. During an information transmission these bits are still located in their original position. But if the trigger signal is not applied, the chip only consumes a standby current which is less than 1μA.

The address pins are usually preset to transmit data codes with particular security codes by the DIP switches or PCB wiring, while the data is selected using push buttons or electronic switches.

The following figure shows an application using the HT680:



The transmitted information is as shown:

Pilot & Sync.	A0	A1	A2	A3	A4	A5	A6	A7	A8	A9	AD10	AD11
	0	Z	0	1	Z	Z	1	Z	0	0	Z	Z
—	AD12	AD13	AD14	AD15	AD16	AD17						
	Z	Z	Z	1	Z	Z						

Z: floating

Address/Data Sequence

The following provides a table of address/data sequence for various models of the 3¹⁸ series encoders.

Part No.	Address/Data Bits											
	0~3	4	5	6~9	10	11	12	13	14	15	16	17
HT600	A0~A3	A4	—	A6~A9	—	AD11	AD12	AD13	AD14	AD15	—	—
HT680	A0~A3	—	—	A6~A9	—	AD11	AD12	—	AD14	AD15	—	—
HT6207	A0~A3	A4	—	A6~A9	—	A11	D12	D13	D14	D15	==	==

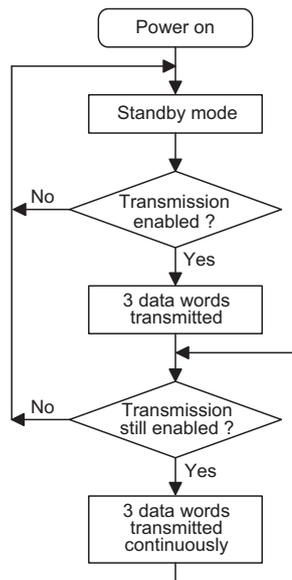
Note: "—" is a dummy code which is left "open" and not bonded out.

"==" is a dummy code which is set low and not bonded out.

Transmission Enable

For the TE trigger type of encoders, transmission is enabled by applying a high signal to the TE pin. But for the Data trigger type of encoders, it is enabled by applying a high signal to one of the data pins D12~D15.

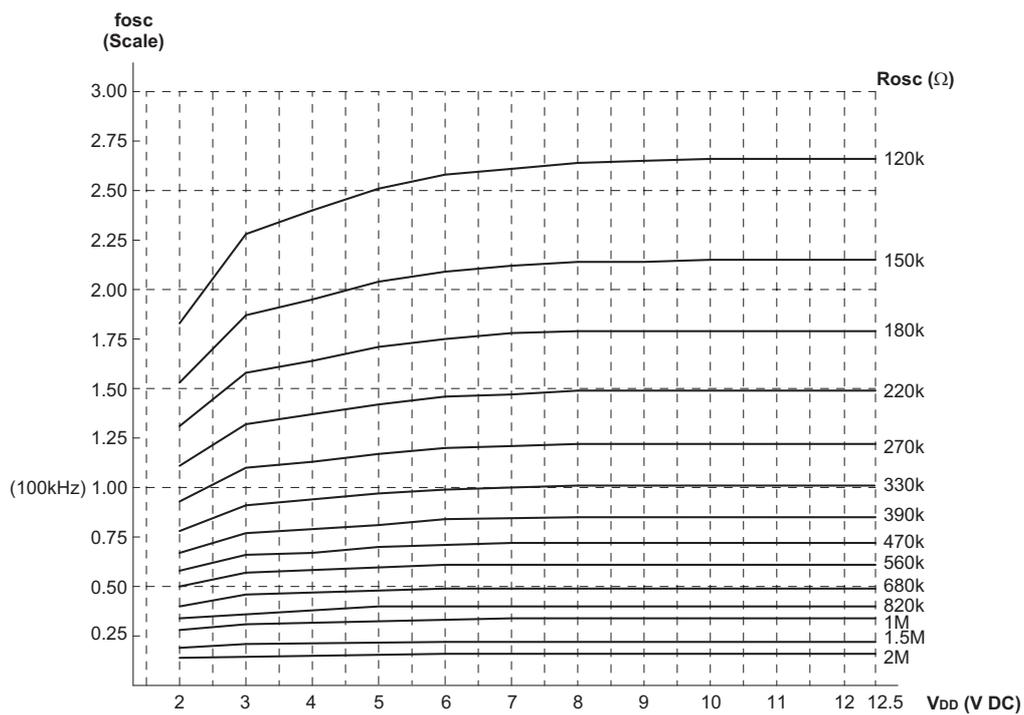
Flowchart



Note: D12~D15 are transmission enables of the HT6207.

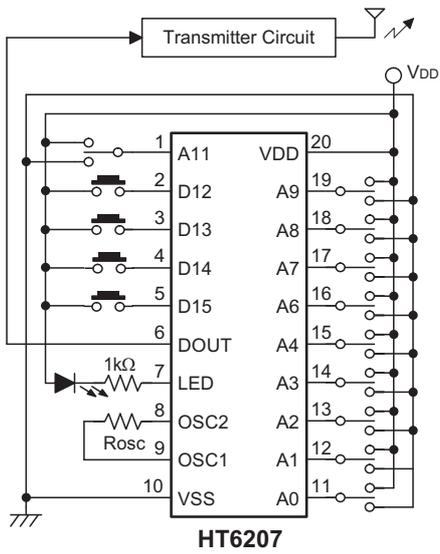
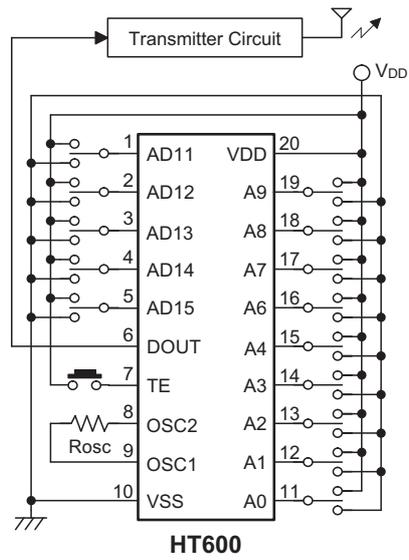
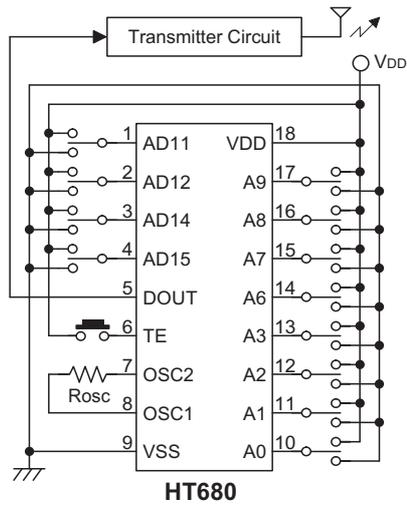
TE is the transmission enable of the HT600/HT680.

Oscillator Frequency vs. Supply Voltage



The recommended oscillator frequency is f_{OSCD} (decoder) \cong f_{OSCE} (encoder)

Application Circuits



Package Information

18-pin DIP (300mil) Outline Dimensions

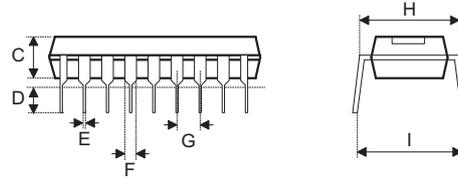
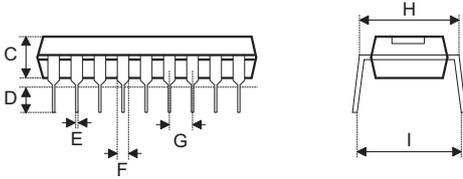
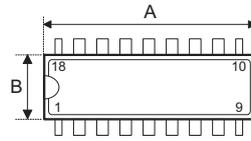
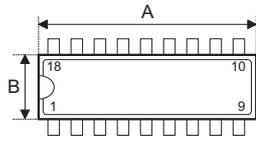


Fig1. Full Lead Packages

Fig2. 1/2 Lead Packages

- MS-001d (see fig1)

Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	880	—	920
B	240	—	280
C	115	—	195
D	115	—	150
E	14	—	22
F	45	—	70
G	—	100	—
H	300	—	325
I	—	—	430

- MS-001d (see fig2)

Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	845	—	880
B	240	—	280
C	115	—	195
D	115	—	150
E	14	—	22
F	45	—	70
G	—	100	—
H	300	—	325
I	—	—	430

- MO-095a (see fig2)

Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	845	—	885
B	275	—	295
C	120	—	150
D	110	—	150
E	14	—	22
F	45	—	60
G	—	100	—
H	300	—	325
I	—	—	430

20-pin DIP (300mil) Outline Dimensions

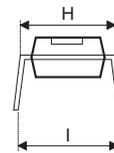
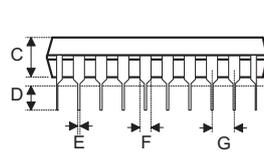
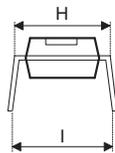
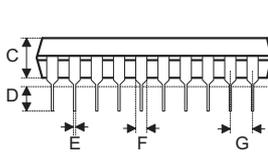
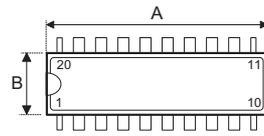
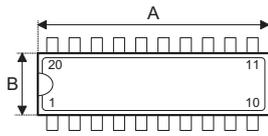


Fig1. Full Lead Packages

Fig2. 1/2 Lead Packages

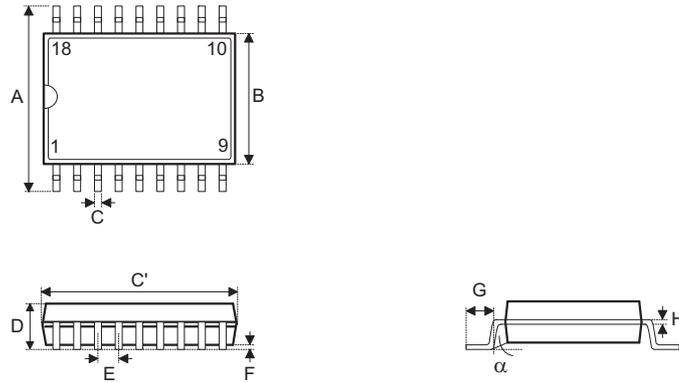
- MS-001d (see fig1)

Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	980	—	1060
B	240	—	280
C	115	—	195
D	115	—	150
E	14	—	22
F	45	—	70
G	—	100	—
H	300	—	325
I	—	—	430

- MO-095a (see fig2)

Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	945	—	985
B	275	—	295
C	120	—	150
D	110	—	150
E	14	—	22
F	45	—	60
G	—	100	—
H	300	—	325
I	—	—	430

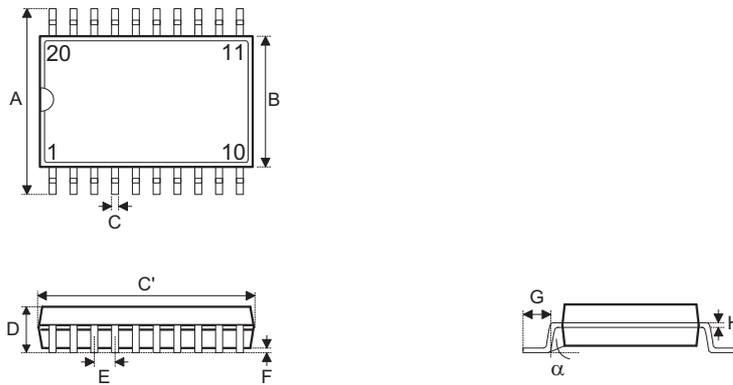
18-pin SOP (300mil) Outline Dimensions



• MS-013

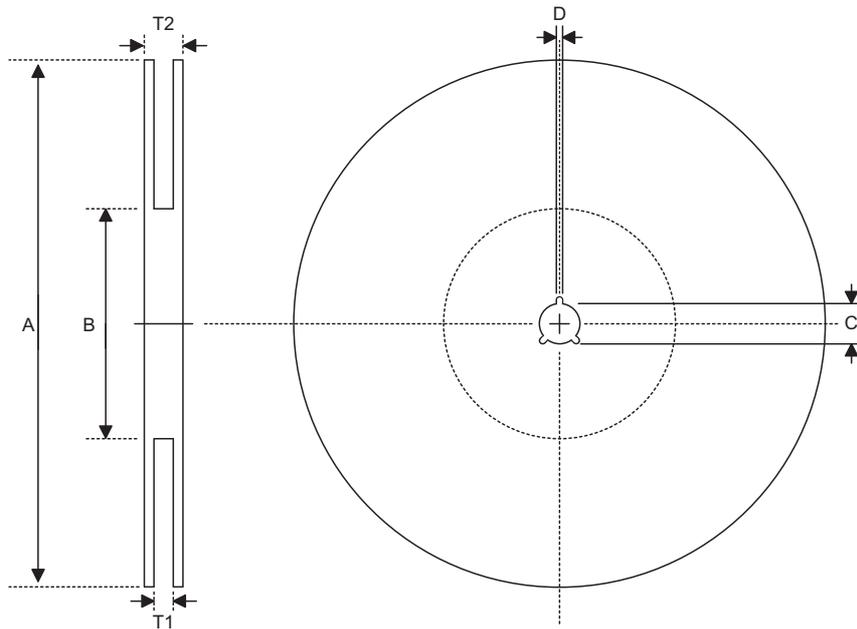
Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	393	—	419
B	256	—	300
C	12	—	20
C'	447	—	463
D	—	—	104
E	—	50	—
F	4	—	12
G	16	—	50
H	8	—	13
α	0°	—	8°

20-pin SOP (300mil) Outline Dimensions



• MS-013

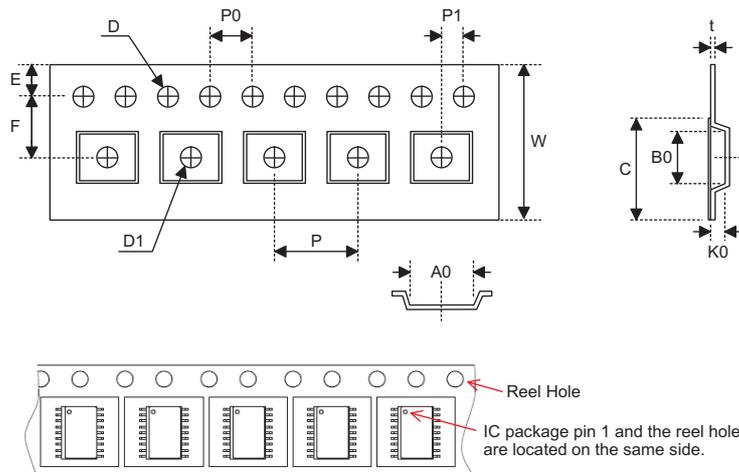
Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	393	—	419
B	256	—	300
C	12	—	20
C'	496	—	512
D	—	—	104
E	—	50	—
F	4	—	12
G	16	—	50
H	8	—	13
α	0°	—	8°

Product Tape and Reel Specifications
Reel Dimensions

SOP 18W

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	330.0±1.0
B	Reel Inner Diameter	100.0±1.5
C	Spindle Hole Diameter	13.0 ^{+0.5/-0.2}
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	24.8 ^{+0.3/-0.2}
T2	Reel Thickness	30.2±0.2

SOP 20W

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	330.0±1.0
B	Reel Inner Diameter	100.0±1.5
C	Spindle Hole Diameter	13.0 ^{+0.5/-0.2}
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	24.8 ^{+0.3/-0.2}
T2	Reel Thickness	30.2±0.2

Carrier Tape Dimensions

SOP 18W

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	24.0 ^{+0.3/-0.1}
P	Cavity Pitch	16.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	11.5±0.1
D	Perforation Diameter	1.5±0.1
D1	Cavity Hole Diameter	1.50 ^{+0.25/-0.00}
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	10.9±0.1
B0	Cavity Width	12.0±0.1
K0	Cavity Depth	2.8±0.1
t	Carrier Tape Thickness	0.30±0.05
C	Cover Tape Width	21.3±0.1

SOP 20W

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	24.0 ^{+0.3/-0.1}
P	Cavity Pitch	12.0±0.1
E	Perforation Position	1.75±0.10
F	Cavity to Perforation (Width Direction)	11.5±0.1
D	Perforation Diameter	1.5 ^{+0.1/-0.0}
D1	Cavity Hole Diameter	1.50 ^{+0.25/-0.00}
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	10.8±0.1
B0	Cavity Width	13.3±0.1
K0	Cavity Depth	3.2±0.1
t	Carrier Tape Thickness	0.30±0.05
C	Cover Tape Width	21.3±0.1

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